ABSTRACT

Wafers W are supported respectively on inner tables 52 of a table 13, and after a strip of sheet S is fed out to the upper surface side of the wafers W, a press roller 14 imparts a press force. The adhesive sheet S is cut along the outer periphery of the wafers by a cutter blade 63 mounted at the free-end side of a robot 15. The robot 15 has a function to exchange the cutter blade 63 with a suction arm 100, to transfer the wafer W from a magazine 200 to the table 13 and to transfer the wafer W stuck with the sheet to the next process.